



## Material Content Data Sheet



<b>Sales Product Name</b>		IPU80R3K3P7		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA002116560						
<b>Package</b>		PG-TO251-3-341		<b>Weight*</b>		386.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.834	0.22	0.22	2156	2156
leadframe	inorganic material	phosphorus	7723-14-0	0.075	0.02		193	
	non noble metal	iron	7439-89-6	0.248	0.06		642	
	non noble metal	copper	7440-50-8	248.124	64.13	64.21	641197	642032
	non noble metal	aluminium	7429-90-5	0.125	0.03	0.03	324	324
wire	non noble metal	aluminium	7429-90-5	0.125	0.03	0.03	324	324
encapsulation	organic material	carbon black	1333-86-4	0.396	0.10		1024	
	plastics	epoxy resin	-	12.016	3.10		31050	
	inorganic material	silicondioxide	60676-86-0	119.628	30.91	34.11	309139	341213
leadfinish	non noble metal	tin	7440-31-5	3.740	0.97	0.97	9665	9665
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1315	1315
solder	non noble metal	tin	7440-31-5	0.026	0.01		66	
	noble metal	silver	7440-22-4	0.032	0.01		82	
	non noble metal	lead	7439-92-1	1.218	0.31	0.33	3147	3295
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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